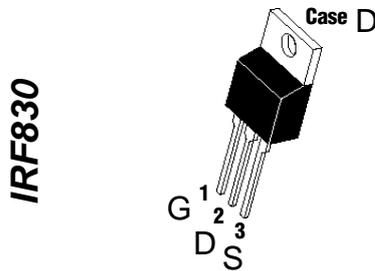




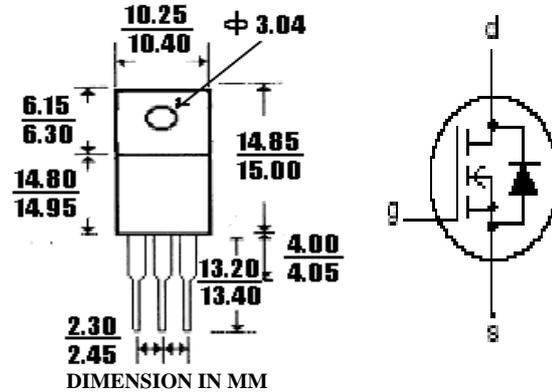
# 4.5A 500V N CHANNEL POWER MOSFET

## Description



TO-220AB

## Mechanical Dimensions



## FEATURES

- Repetitive Avalanche Rated
- Fast switching
- High thermal cycling performance
- Low thermal resistance

## GENERAL DESCRIPTION

N-channel, enhancement mode field-effect power transistor, intended for use in off-line switched mode power supplies, T.V. and computer monitor power supplies, d.c. to d.c. converters, motor control circuits and general purpose switching applications.

The IRF830 is supplied in the SOT78 (TO220AB) conventional leaded package.

## LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DSS}$	Drain-source voltage	$T_j = 25\text{ }^\circ\text{C}$ to $150\text{ }^\circ\text{C}$	-	500	V
$V_{DGR}$	Drain-gate voltage	$T_j = 25\text{ }^\circ\text{C}$ to $150\text{ }^\circ\text{C}$ ; $R_{GS} = 20\text{ k}\Omega$	-	500	V
$V_{GS}$	Gate-source voltage		-	$\pm 30$	V
$I_D$	Continuous drain current	$T_{mb} = 25\text{ }^\circ\text{C}$ ; $V_{GS} = 10\text{ V}$	-	5.9	A
		$T_{mb} = 100\text{ }^\circ\text{C}$ ; $V_{GS} = 10\text{ V}$	-	3.7	A
$I_{DM}$	Pulsed drain current	$T_{mb} = 25\text{ }^\circ\text{C}$	-	24	A
$P_D$	Total dissipation	$T_{mb} = 25\text{ }^\circ\text{C}$	-	125	W
$T_j, T_{stg}$	Operating junction and storage temperature range		-55	150	$^\circ\text{C}$

## AVALANCHE ENERGY LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$E_{AS}$	Non-repetitive avalanche energy	Unclamped inductive load, $I_{AS} = 4.2\text{ A}$ ; $t_p = 0.21\text{ ms}$ ; $T_j$ prior to avalanche = $25\text{ }^\circ\text{C}$ ; $V_{DD} \leq 50\text{ V}$ ; $R_{CS} = 50\text{ }\Omega$ ; $V_{GS} = 10\text{ V}$ ; refer to fig:17	-	287	mJ
$E_{AR}$	Repetitive avalanche energy <sup>1</sup>	$I_{AR} = 5.9\text{ A}$ ; $t_p = 2.5\text{ }\mu\text{s}$ ; $T_j$ prior to avalanche = $25\text{ }^\circ\text{C}$ ; $R_{CS} = 50\text{ }\Omega$ ; $V_{GS} = 10\text{ V}$ ; refer to fig:18	-	10	mJ
$I_{AS}, I_{AR}$	Repetitive and non-repetitive avalanche current		-	5.9	A



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### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base		-	-	1	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	in free air	-	60	-	K/W

### ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 0.25\text{ mA}$	500	-	-	V
$\Delta V_{(BR)DSS} / \Delta T_j$	Drain-source breakdown voltage temperature coefficient	$V_{DS} = V_{GS}; I_D = 0.25\text{ mA}$	-	0.1	-	%/K
$R_{DS(on)}$	Drain-source on resistance	$V_{GS} = 10\text{ V}; I_D = 3\text{ A}$	-	1.2	1.5	$\Omega$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}; I_D = 0.25\text{ mA}$	2.0	3.0	4.0	V
$g_{fs}$	Forward transconductance	$V_{DS} = 30\text{ V}; I_D = 3\text{ A}$	2	3.6	-	S
$I_{DSS}$	Drain-source leakage current	$V_{DS} = 500\text{ V}; V_{GS} = 0\text{ V}$	-	1	25	$\mu\text{A}$
$I_{GSS}$	Gate-source leakage current	$V_{DS} = 400\text{ V}; V_{GS} = 0\text{ V}; T_j = 125\text{ }^\circ\text{C}$	-	30	250	$\mu\text{A}$
		$V_{GS} = \pm 30\text{ V}; V_{DS} = 0\text{ V}$	-	10	200	nA
$Q_{g(tot)}$	Total gate charge	$I_D = 6\text{ A}; V_{DD} = 400\text{ V}; V_{GS} = 10\text{ V}$	-	53	64	nC
$Q_{gs}$	Gate-source charge		-	4	6	nC
$Q_{gd}$	Gate-drain (Miller) charge		-	28	34	nC
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 250\text{ V}; R_D = 39\text{ }\Omega;$	-	10	-	ns
$t_r$	Turn-on rise time	$R_G = 12\text{ }\Omega$	-	33	-	ns
$t_{d(off)}$	Turn-off delay time		-	92	-	ns
$t_f$	Turn-off fall time		-	40	-	ns
$L_d$	Internal drain inductance	Measured from tab to centre of die	-	3.5	-	nH
$L_d$	Internal drain inductance	Measured from drain lead to centre of die	-	4.5	-	nH
$L_s$	Internal source inductance	Measured from source lead to source bond pad	-	7.5	-	nH
$C_{iss}$	Input capacitance	$V_{GS} = 0\text{ V}; V_{DS} = 25\text{ V}; f = 1\text{ MHz}$	-	610	-	pF
$C_{oss}$	Output capacitance		-	96	-	pF
$C_{rss}$	Feedback capacitance		-	54	-	pF

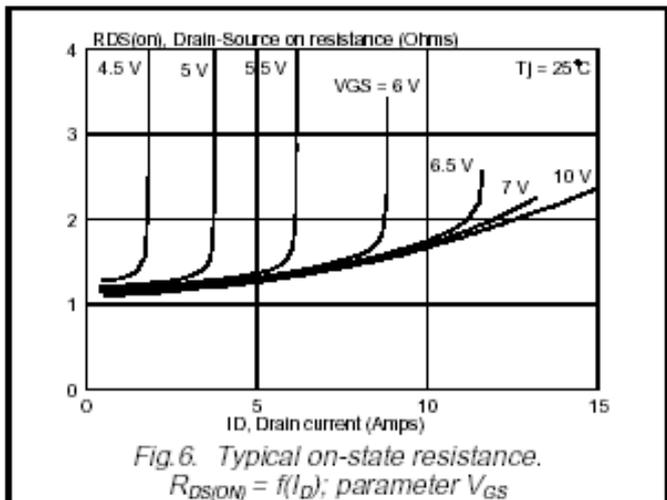
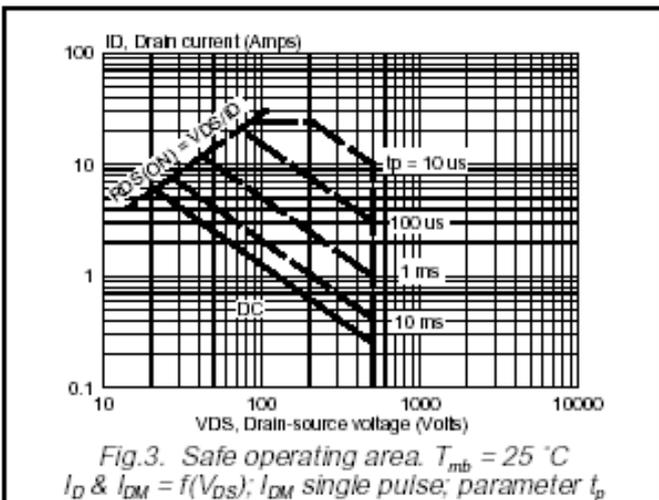
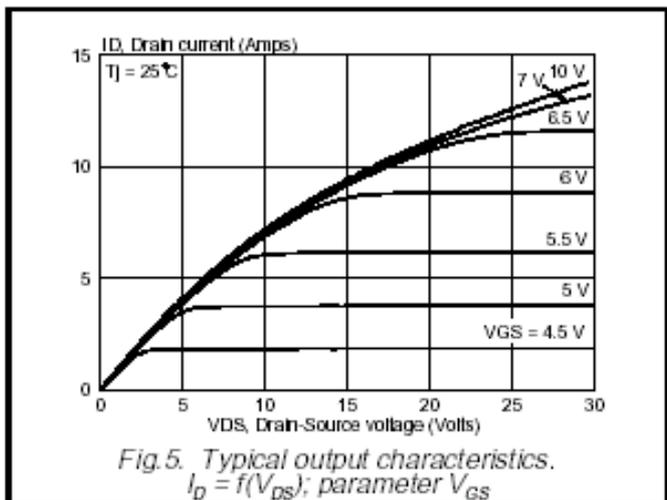
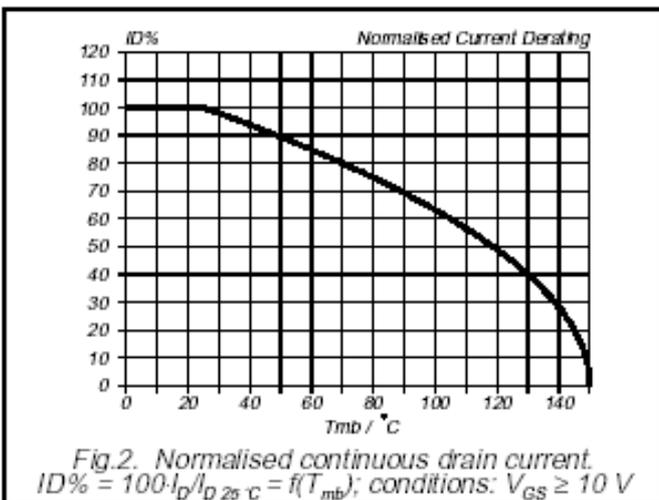
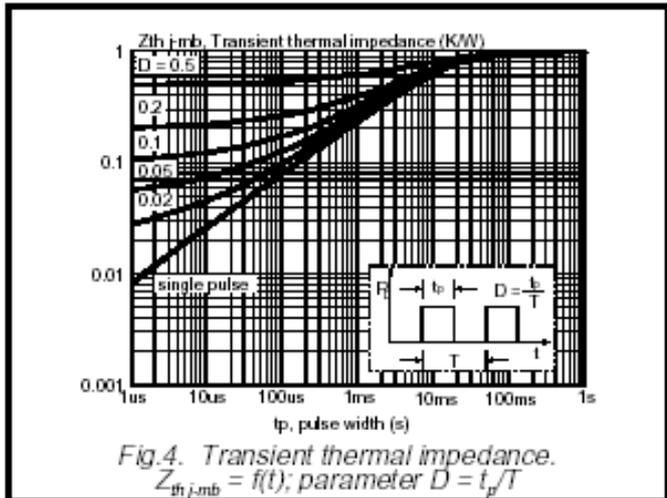
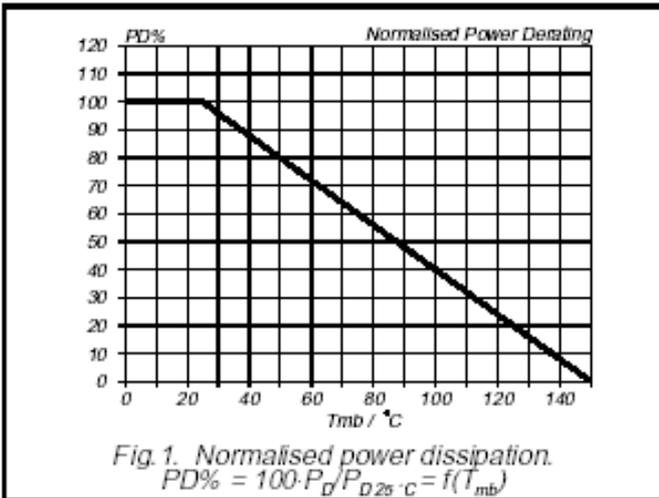
### SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_S$	Continuous source current (body diode)	$T_{mb} = 25\text{ }^\circ\text{C}$	-	-	5.9	A
$I_{SM}$	Pulsed source current (body diode)	$T_{mb} = 25\text{ }^\circ\text{C}$	-	-	24	A
$V_{SD}$	Diode forward voltage	$I_S = 6\text{ A}; V_{GS} = 0\text{ V}$	-	-	1.2	V
$t_{rr}$	Reverse recovery time	$I_S = 6\text{ A}; V_{GS} = 0\text{ V}; di/dt = 100\text{ A}/\mu\text{s}$	-	390	-	ns
$Q_{rr}$	Reverse recovery charge		-	4	-	$\mu\text{C}$

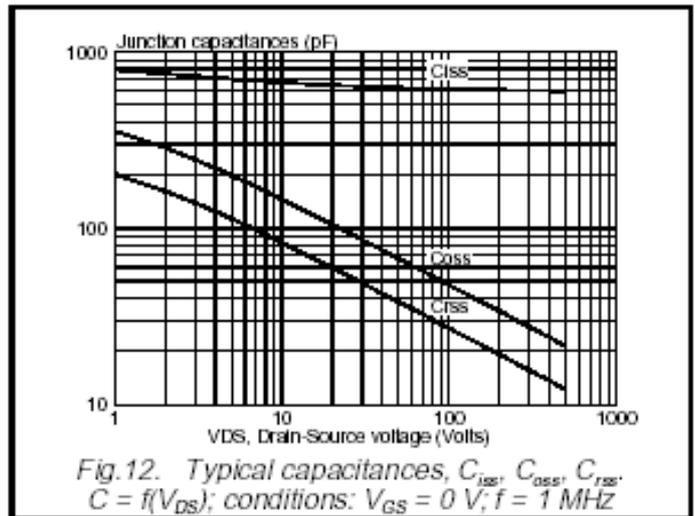
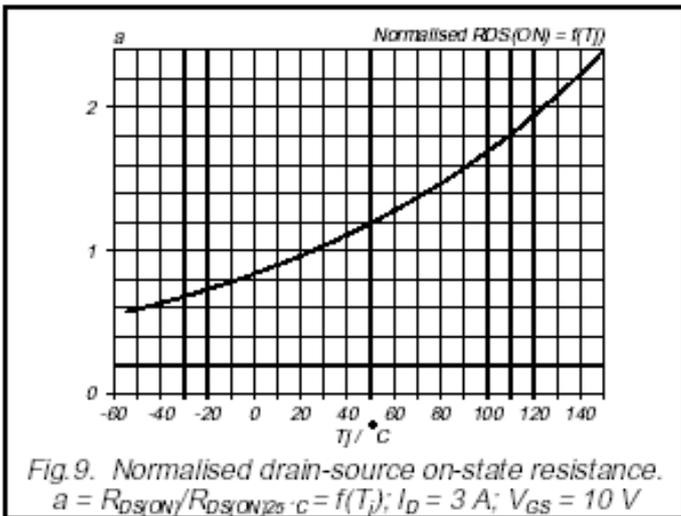
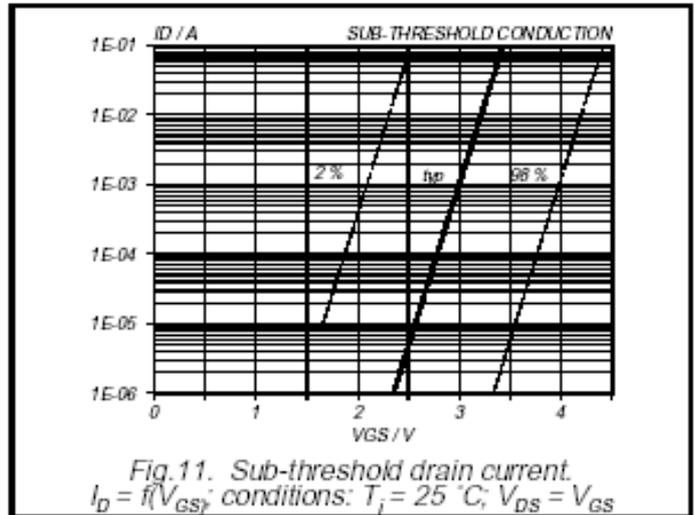
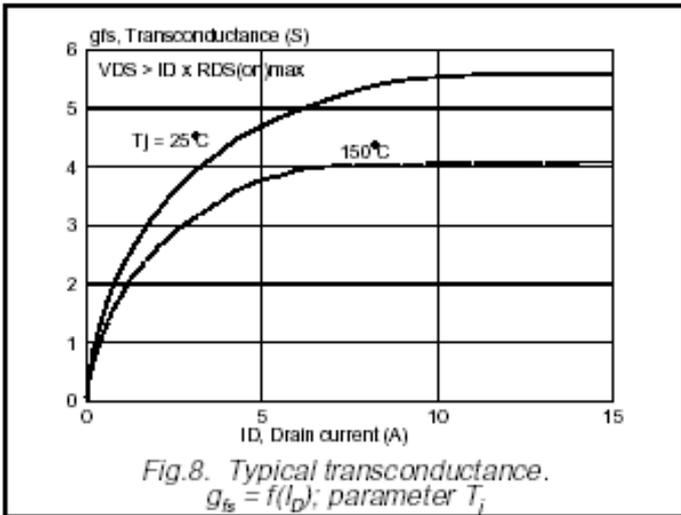
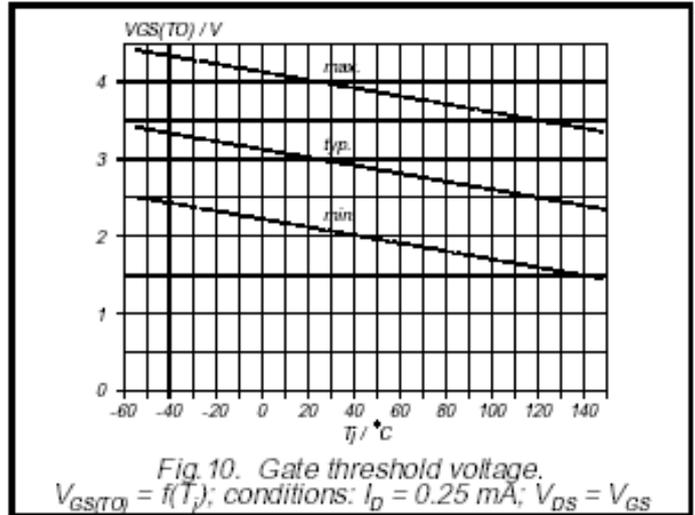
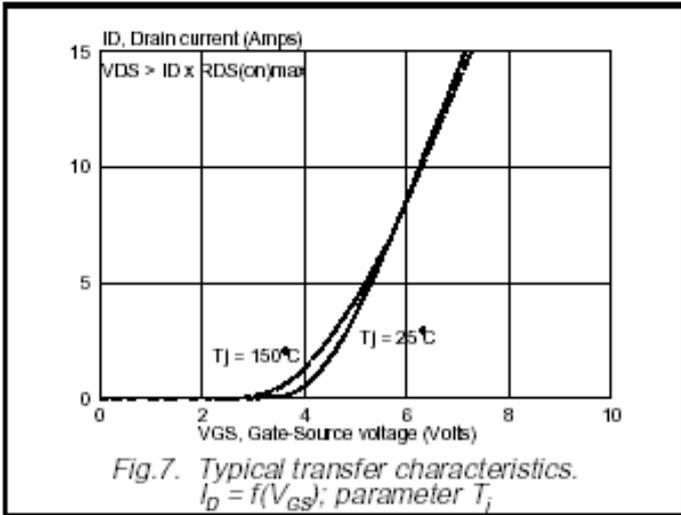


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